

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
Jia-Horng Shieh		03/03/2006
Pi-Hai Liu		03/03/2006
RECEIVING PARTY DATA		
Name:	MediaTek Inc.	
Street Address:	5F, No. 1-2, Innovation Road 1, Science-Based Industrial Park	
City:	Hsin-Chu Hsien	
State/Country:	TAIWAN	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	11277351	
CORRESPONDENCE DATA		
Fax Number:	(806)498-6673	
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>		
Phone:	3027291562	
Email:	Patent.admin.uspto.cr@naipo.com	
Correspondent Name:	WINSTON HSU	
Address Line 1:	P.O.BOX 506	
Address Line 4:	Merrifield, VIRGINIA 22116	
ATTORNEY DOCKET NUMBER:	MTKP0326USA	
NAME OF SUBMITTER:	WINSTON HSU	
Total Attachments: 2 source=MTKP0326-0-A1-ASS#page1.tif source=MTKP0326-0-A1-ASS#page2.tif		

CH \$40.00 11277351

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Jia-Horng Shieh Nationality: R.O.C.

Address: 5F, No. 2, Alley 8, Lane 37, Nanshan Rd., Jhonghe City, Taipei County, Taiwan, R.O.C.

Name: Pi-Hai Liu Nationality: R.O.C.

Address: No. 19, Alley 3, Lane 101, Tung-Yuan St., Wan-Hua District, Taipei City, Taiwan, R.O.C.

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: MediaTek Inc.

Address: 5F, No. 1-2, Innovation Road 1, Science-Based Industrial Park, Hsin-Chu Hsien 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

**"SYSTEM AND METHOD FOR MODULATION AND DEMODULATION USING CODE  
SUBSET CONVERSION"**

Which is found in :

- (a) + U.S. patent application executed on even date  
(b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_  
(c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_  
(d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

## PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this 2006/3/3 Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Jia-Horng Shieh

Pi-Hai Liu

Signature of INVENTOR

Jia-Horng Shieh

Pi-Hai Liu

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RECORDED: 03/28/2006

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